Serial No.: 09/663,021 Group Art Unit: 2815

AMENDMENT

IN THE CLAIMS:

Please replace pending claim 1 with the following clean amended claim 1:

SAP!

- 1. (Amended) A semiconductor device, comprising:
- a semiconductor with a dielectric layer formed thereon, wherein said dielectric layer overlays a region on said semiconductor and has a channel opening provided therein;
- a first barrier layer disposed in said dielectric layer lining said channel opening, said first barrier layer of a metallic barrier material;
- a conductive material disposed in said first barrier layer in said channel opening; and
- a second barrier layer disposed over said conductive layer in said channel opening, said second barrier layer of a metallic barrier material, whereby said conductive material is totally enclosed in metallic barrier material.
- Please add the following new claims 19 and 20:
 - 19. (New) A semiconductor device, comprising:
 - a semiconductor;
 - a dielectric layer formed on the semiconductor, said dielectric layer having a channel opening provided therein;
 - a recessed channel in said channel opening including:
 - a first barrier layer disposed in said channel opening, said first barrier layer of a metallic barrier material; and
 - a conductive material disposed in said first barrier layer; and
 - a self-aligned semiconductor interconnect barrier disposed over said recessed channel in said channel opening.
- 20. (New) The semiconductor device as claimed in claim 19 wherein said first barrier layer and said self-aligned semiconductor interconnect barrier totally enclose the conductive materi 1.